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Datasheet

Nexcom

NDiS V1100

Fanless Embedded Box PC Powered by 11th Gen Intel® Core™ Processor



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Main Features

- 11th Gen Intel® Core™ (Tiger Lake UP3) processor SoC
- Dual non-ECC DDR4 3200 SO-DIMM, support up to 32Gb
- 4 x HDMI 2.0, support 4K@60Hz
- Dual LAN ports and 3 x USB 3.0 ports
- Onboard M.2 2280 Key M with PCIe x4 signal for storage modules
- Onboard mini-PCIe for optional Wi-Fi or LTE modules
- Fanless design

Product Overview

Powered by the latest 11th Gen Intel® Core™ (Tiger Lake UP3) processor, NDiS V1100 digital signage player can handle very rich multimedia contents. With Intel® processor low power consumption and new Intel® Iris® X^e graphics, the platform deliver powerful graphics offering stunning visuals for compelling 4K content creation and media playback. In addition, NDiS V1100 series supports four display output with flexible integration for various peripherals such as, scanners, readers, and many more. NDiS V1100 series is a fanless player with room temperature and extended temperature durability further extends to outdoor usage like QSR drive through kiosks, box office displays, information stands, bus stops, or digital transit information signs. It is also ideal as a digital signage player delivering enhanced performance and new immersive experiences for advertising, hospitality and brand promotion applications.

Specifications

CPU Support

- Onboard 11th Gen Intel® Core™ i3-1115G4E processor, dual core, 2.2 GHz, 6M cache
- Onboard 11th Gen Intel® Core™ i5-1145G7E processor, quad core, 1.5 GHz, 8M cache
- Onboard 11th Gen Intel® Core™ i7-1185G7E processor, quad core, 1.8 GHz, 12M cache (by request)

Chipset

- SoC (codenamed Tiger Lake UP3)

Main Memory

- 2 x 260-pin DDR4 SO-DIMM, supports non-ECC, un-buffered memory up to 64G

Graphics & Display

- Intel® UHD graphics on i3 processor
- Intel® Iris® X^e graphics on i5 and i7 processor
- 4 x HDMI, support 4096 x 2160@60Hz

Interface-Rear

- 1 x power button with LED

- 1 x HDD LED
- 2 x DB9
 - COM1: RS232/422/485
 - COM2: RS232

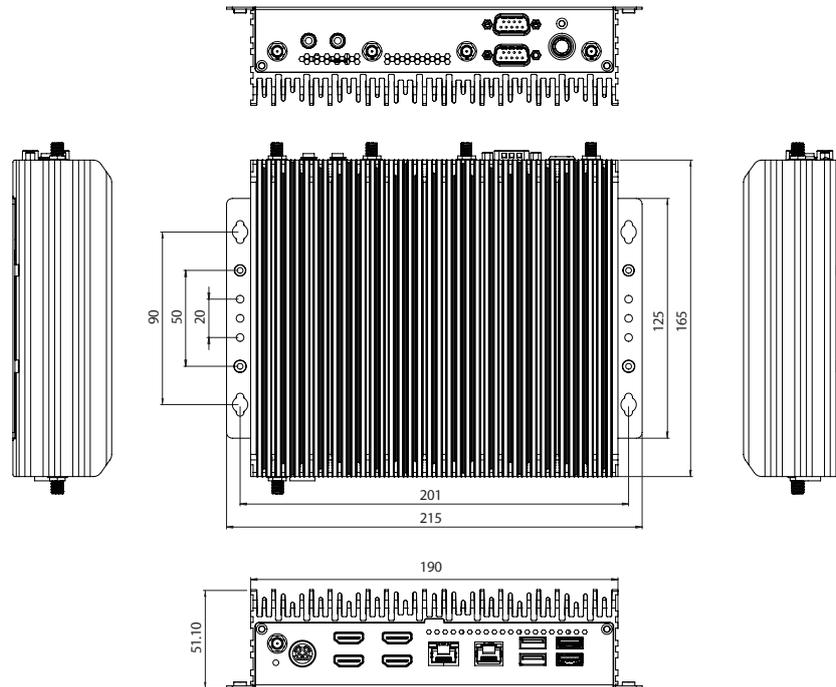
I/O Interface-Rear

- 1 x 4-pin DC Jack, 12V
- 4 x HDMI
- 2 x RJ45 Intel® Gigabit LAN port
 - 1 x Intel® I219-LM GbE PHY
 - 1 x Intel® I225-V GbE LAN
- 3 x USB 3.0
- 1 x USB 2.0

I/O Interface-Internal

- 4 x USB 2.0, internal connector
- 1 x Mic-in/Line out, internal connector
- 1 x Speaker out with 2W/4Ω amplifier, internal connector
- 8 x GPIO pin header for 4 x GPI and 4 x GPO
- 1 x 4-pin connector for PWM smart fan
- Onboard TPM2.0

Dimension Drawing



Storage

- 1 x M.2 2280 Key M (PCIe Gen4 x4, SATA III), support optional storage modules
- 1 x SATA & SATA power connector

Expansion

- 1 x M.2 3052 Key B, support optional 5G modules
- 1 x mini-PCIe, support optional 4G/Wi-fi/Bluetooth modules

Power Supply

- 1 x External 96W AC/DC power adapter
- Input: 100V AC to 240V AC
- Output: DC+12VDC

Environment

- Operating temperature: V1100 (0°C to 45°C)
- Storage temperature: -20°C to 80°C
- Humidity: 10 to 90% (non-condensing)

Certification

- CE Approval
- FCC Class A

Dimensions

- 190mm (W) x 165mm (D) x 51.1mm (H) (without wall mount bracket)

Operating System Support

- Win10/Linux

Ordering Information

- **NDiS V1100-i3 (P/N: 10W00110000X0)**
11th Gen Intel® Core™ i3-1115G4E processor fanless system, 0°C~45°C
- **NDiS V1100-i5 (P/N: 10W00110001X0)**
11th Gen Intel® Core™ i5-1145G7E processor fanless system, 0°C~45°C

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